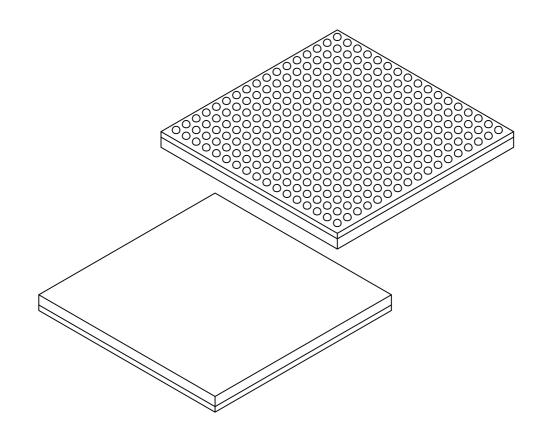
289-Ball Low Profile Fine Pitch Ball Grid Array (AMB) - 14x14x1.4 mm Body [LFBGA] Atmel Legacy Global Package Code CCZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	289		
Pitch	е	0.80 BSC		
Overall Height	Α	-	-	1.40
Ball Height	A1	0.27	0.32	0.37
Molded Cap Thickness	A2	0.70 REF		
Substrate Thickness	A3	0.26 REF		
Overall Length	D	14.00 BSC		
Overall Width	E	14.00 BSC		
Terminal Diameter	b	0.38	0.43	0.48

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.